

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Herald M. Baldonado

Serial No.:

10/066,421

Filed: 01/30/2002

For: Method and System of Wire Bonding Using

Interposer Pads

TI No.:

Art Unit:

Examiner: Clark,

Conf. No.: 5110

NOTICE OF APPEAL

Commissioner For Patents Alexandria, VA 22313-1450

Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alguandria, VA 22313-

Applicant hereby appeals to the Board of Appeals from the decision dated, of the Primary Examiner finally rejecting Claims .

Charge the fee of \$320.00 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

Texas Instruments Incorporated

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320.00 DA

Respectfully submitted,

Michael K. Skrehot

Attorney for Applicant

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